Preliminary Product Information Sheet

EPO-TEK® H74G (*formerly 114-50*)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date: September 2017
Rev: II
No. of Components: Two
Mix Ratio by Weight: 10 : 0.3
Specific Gravity: Part A: 2.11 Part B: 1.02
Pot Life: 2 Hours
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 5 Minutes
100°C / 20 Minutes

NOTES:
- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- If product crystalizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.

Product Description: A two component, thermally conductive epoxy designed for hybrid circuit assembly including die attach, substrate attach, lid-seal, heat dissipation, and hermetic sealing in general. It is a fluorescent version of EPO-TEK® H74 for inline inspection.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	**Cure condition:** 150°C / 1 Hour	
Color (before cure):	Part A: Grey	Part B: Amber
Consistency:	Smooth pourable paste	
Viscosity (23°C) @ 5 rpm:	61,059	cPs
Thixotropic Index:	2.1	
Glass Transition Temp:	127	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	21	x 10^{-6} in/in°C
Above Tg:	95	x 10^{-6} in/in°C
Shore D Hardness:	90	
Lap Shear @ 23°C:	1,656	
Die Shear @ 23°C:	15	Kg
Degradation Temp:	425	°C
Weight Loss:		
@ 200°C:	0.29	%
@ 250°C:	0.50	%
@ 300°C:	0.80	%
Suggested Operating Temperature:	< 350	°C (Intermittent)
Storage Modulus:	860,430	psi
Particle Size:	≤ 50	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.3	W/mK
Volume Resistivity @ 23°C:	≥ 4 x 10^{12}	Ohm-cm
Dielectric Constant (1KHz):	4.95	
Dissipation Factor (1KHz):	0.007	

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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